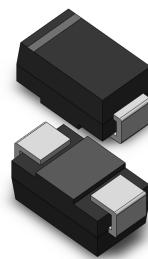


VOLTAGE RANGE: 100 - 200V
CURRENT: 1.0 A

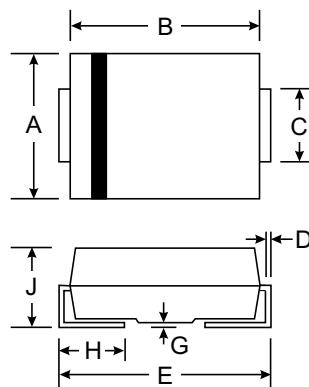
Features

- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- Ultrafast recovery times for high efficiency
- Low forward voltage, low power loss



Mechanical Data

- Case: SMA(DO-214AC) Molded Plastic
- Case Material - UL Flammability Rating Classification 94V-0
- Terminals: Solder Plated Terminal - Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band or Cathode Notch
- Approx. Weight: SMA 0.064 grams



SMA(DO-214AC)		
Dim	Min	Max
A	2.29	2.92
B	4.00	4.60
C	1.27	1.63
D	0.15	0.31
E	4.80	5.59
G	0.10	0.20
H	0.76	1.52
J	2.01	2.62

All Dimensions in mm

Maximum Ratings and Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	ESH1B	ESH1C	ESH1D	Unit
	Marking	EHB	EHC	EHD	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	100	150	200	V
RMS Reverse Voltage	V _{R(RMS)}	70	105	140	V
Average Rectified Output Current @ $T_L = 120^\circ\text{C}$	I _O		1.0		A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}		50		A
Forward Voltage @ $I_F = 1.0\text{A}$	V _{FM}		0.90		V
Peak Reverse Current @ $T_A = 25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_A = 100^\circ\text{C}$	I _{RM}		1.0 25		μA
Reverse Recovery Time (Note 1)	t _{rr}		25		nS
Typical Junction Capacitance (Note 2)	C _j		25		pF
Typical Thermal Resistance (Note 3)	R _{θ JL}		30		°C/W
Operating and Storage Temperature Range	T _j , T _{STG}		-65 to +150		°C

Note: 1. Measured with I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A. See figure 5.
 2. Measured at 1.0 MHz and applied reverse voltage of 4.0 V DC.
 3. Mounted on P.C. Board with 8.0mm² land area.

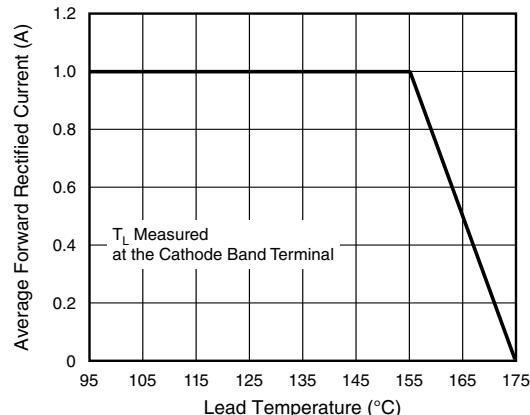
RATINGS AND CHARACTERISTICS CURVES ($T_A = 25^\circ\text{C}$ unless otherwise noted)


Figure 1. Maximum Forward Current Derating Curve

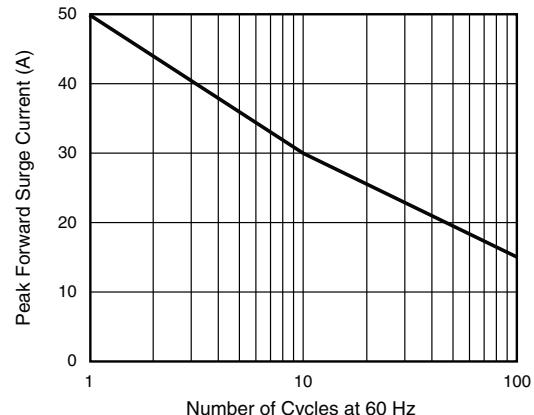


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

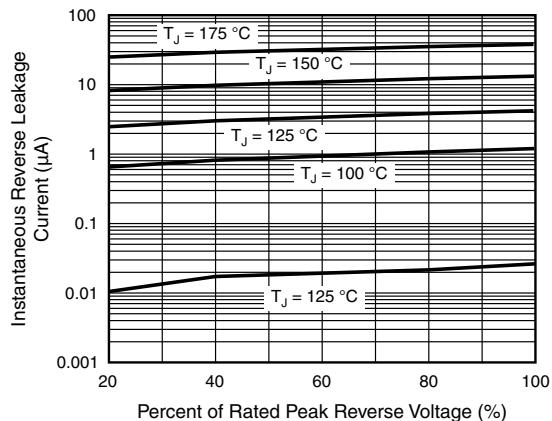


Figure 3. Typical Reverse Leakage Characteristics

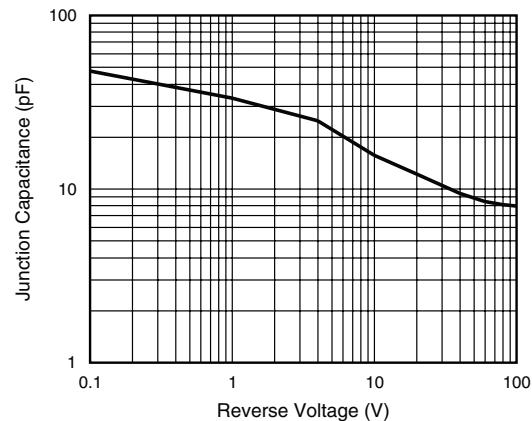


Figure 5. Typical Junction Capacitance

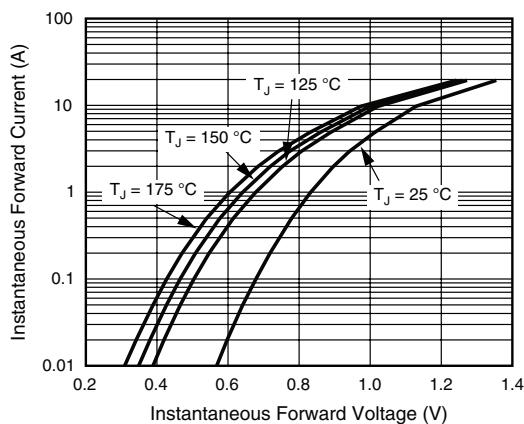


Figure 4. Typical Instantaneous Forward Characteristics

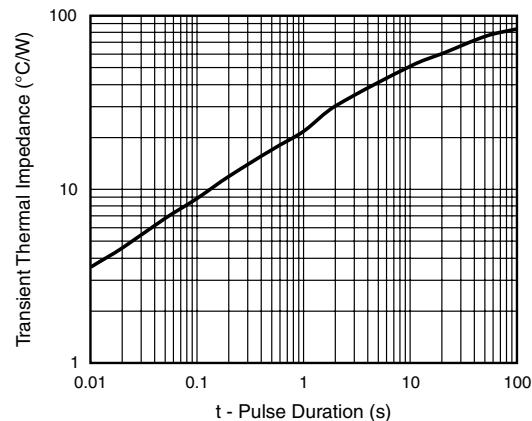


Figure 6. Typical Transient Thermal Impedance